

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in this application.

1. (Currently Amended) A method of forming a ~~pattern on an article~~ housing for a mobile telephone having electronic components, the method comprising the steps of:
applying a carrier material to a substrate to provide ~~the~~ a pattern, the carrier material carrying a seeding substance to allow application of a metallic material thereto;
moulding the substrate to form ~~the article~~ a moulded substrate; and
applying the metallic material to the seeding substance on the carrier material; thereby forming a metallic pattern for forming at least one electrical connection for electronic components of the mobile telephone.
2. (Original) A method according to claim 1, wherein the carrier material is an ink and is applied to the substrate by printing.
3. (Original) A method according to claim 2, wherein the ink incorporates a binder material for fixing the sealing substance on the substrate.
4. (Original) A method according to claim 3, wherein the step of moulding the substrate can involve stretching some of the substrate, wherein the binder material is selected from materials capable of stretching to at least the same extent as the substrate.
5. (Original) A method according to claim 3, wherein the binder material is one or more selected from the group consisting of acrylic resins, silicone, polyurethanes, polycarbonates, polyesters, rosins, rubbers, polyimides, polyolefins, derivatives of polyolefins, polystyrenes, derivatives of polystyrenes and polymer alloys such as acrylonitrile-butadiene-styrene, acrylstyrene.
6. (Original) A method according to claim 1, wherein the seeding substance comprises a plurality of metal particles in the carrier material.
7. (Original) A method according to claim 6, wherein the step of applying the metallic material to the carrier material comprises plating the metallic material onto the metallic

particles in the carrier material.

8. (Original) A method according to claim 7, wherein the step of plating the metallic material onto the carrier material comprises at least one step selected from the group consisting of electroplating and electroless plating.

9. (Original) A method according to claim 6, wherein the metal particles are present in a range of 0.005 wt% to 10 wt%.

10. (Original) A method according to claim 6, wherein the metal particles are present in a range of 0.05 wt% to 5 wt%.

11. (Original) A method according to claim 6, wherein the metal particles are present in a range of 0.1 wt% to 2 wt%.

12. (Original) A method according to claim 6, wherein the metal particles have an average size of no greater than 0.15 μm .

13. (Original) A method according to claim 6, wherein the metal particles have an average size in the range of 0.003 μm to 0.05 μm .

14. (Original) A method according to claim 6, wherein the metal particles have an average size in the range of 0.003 μm to 0.015 μm .

15. (Currently Amended) A method according to claim 1, wherein the step of moulding the substrate comprises press moulding the substrate to form the ~~article~~moulded substrate.

16. (Original) A method according to claim 1, wherein the substrate comprises a plastic sheet.

17. (Original) A method according to claim 16 wherein the plastic sheet comprises a thermoplastic material.

18. (Original) A method according to claim 1, wherein the step of moulding the substrate is carried out before the step of applying the metallic material to the carrier material.

19. (Original) A method according to claim 1, wherein the pattern is a line pattern to define electrical connections.

20-41. (Canceled)

42. (New) A method of forming a pattern on an article comprising:

applying a carrier material to a substrate to provide a pattern, the carrier material carrying a seeding substance to allow application of a metallic material thereto and a binder material for fixing the seeding substance on the substrate;

moulding the substrate to form the article; and

applying the metallic material to the seeding substance on the carrier material, wherein the binder material is one or more selected from the group consisting of acrylic resins, silicone, polyurethanes, polycarbonates, polyesters, rubbers, polyimides, polyolefins, derivatives of polyolefins, polystyrenes, derivatives of polystyrenes and polymer alloys.

43.(New) The method of claim 42, wherein the binder material comprises a polymer alloy selected from the group acrylonitrile-butadiene-styrene and acrylstyrene.